

Please re-write claim 2 as follows:

SUB 7
FI 19
2. The method of claim 1 further comprising the step of choosing said etchant to etch said sacrificial material without substantially etching said substrate or said microstructure..

• Please re-write claim 4 as follows:

SUB 7
FI 20
4. The method of claim 2 wherein said etchant is oxygen plasma, said sacrificial material is photoresist and wherein said structural material is aluminum.

- Please delete claims 5-20.
- Please add claims 21-23:

SUB 7
FI 21
21. The method of claim 1 wherein said etchant has a high etch rate with respect to said sacrificial material and a low etch rate with respect to said structural material.

22. The method of claim 21 wherein said structural material is resistant to said etchant.

23. The method of claim 21 wherein said structural material is self-passivating with respect to said etchant.

REMARKS

In paragraph 1 under the Drawing section, the Examiner has objected to the drawings as failing to comply with 37 C.F.R. § 1.84 (p)(5) because they do not include reference numbers 7 and 9 used on page 4, line 30. In response, the Applicant has modified page 4, lines 7 and 9 to remove the offending reference numbers.

In paragraph 1 of the Specification section, the Examiner has objected to the Specification based on formalities wherein figures were referenced using lower case letters. In